

# < HIGH VOLTAGE DIODE MODULES >

## RM800DG-90F

HIGH POWER SWITCHING USE  
INSULATED TYPE

High Voltage Diode Modules

RM800DG-90F



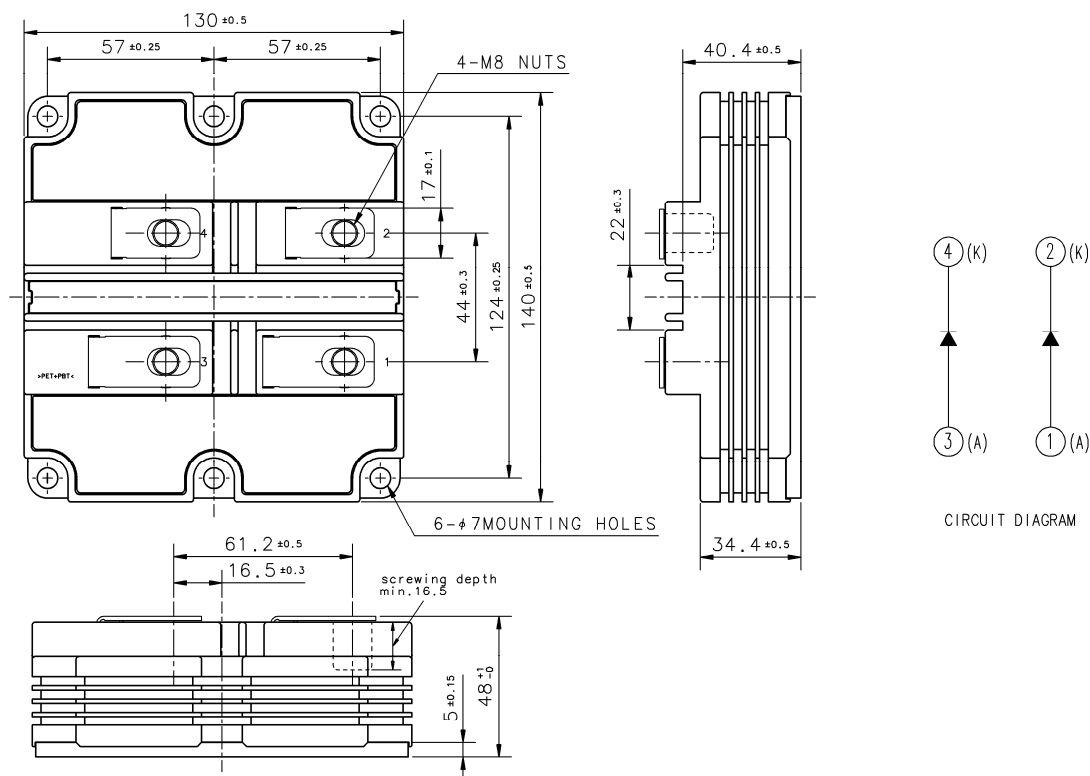
- $I_F$ .....800A
- $V_{RRM}$ .....4500V
- 2-element in a Pack
- High insulated Type
- Soft Recovery Diode
- AISiC Baseplate

### APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

### OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



## &lt; HIGH VOLTAGE DIODE MODULES &gt;

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**MAXIMUM RATINGS**

Symbol	Item	Conditions	Ratings	Unit
$V_{RRM}$	Repetitive peak reverse voltage	$T_j = -40 \dots +125^\circ\text{C}$	4500	V
		$T_j = -50^\circ\text{C}$	4400	
$I_F$	Forward current	DC, $T_c = 65^\circ\text{C}$	800	A
$I_{FSM}$	Surge forward current	$T_{j\_start} = 125^\circ\text{C}$ , $t_p = 10$ ms, Half-sine wave, $V_R = 0$ V	6.5	kA
$I_t^2$	Surge current load integral		211	$\text{kA}^2\text{s}$
$P_{tot}$	Maximum power dissipation	$T_c = 25^\circ\text{C}$	4160	W
$V_{iso}$	Isolation voltage	RMS, sinusoidal, $f = 60$ Hz, $t = 1$ min.	10200	V
$V_e$	Partial discharge extinction voltage	RMS, sinusoidal, $f = 60$ Hz, $Q_{PD} \leq 10$ pC	3500	V
$T_j$	Junction temperature		$-50 \sim +150$	$^\circ\text{C}$
$T_{jop}$	Operating junction temperature		$-50 \sim +125$	$^\circ\text{C}$
$T_{stg}$	Storage temperature		$-55 \sim +125$	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS**

Symbol	Item	Conditions		Limits			Unit
				Min	Typ	Max	
I <sub>RRM</sub>	Repetitive reverse current	V <sub>RM</sub> = V <sub>RRM</sub>	T <sub>J</sub> = 25°C	—	—	1.0	mA
			T <sub>J</sub> = 125°C	—	3.0	—	
V <sub>FM</sub>	Forward voltage	I <sub>F</sub> = 800 A	T <sub>J</sub> = 25°C	—	2.55	—	V
			T <sub>J</sub> = 125°C	—	2.85	3.45	
t <sub>rr</sub>	Reverse recovery time	V <sub>CC</sub> = 2800 V I <sub>F</sub> = 800 A	T <sub>J</sub> = 25°C	—	0.70	—	μs
			T <sub>J</sub> = 125°C	—	0.90	—	
I <sub>rr</sub>	Reverse recovery current	-d <sub>i</sub> /d <sub>t</sub> = 2600 A/μs @ T <sub>J</sub> = 25°C -d <sub>i</sub> /d <sub>t</sub> = 2400 A/μs @ T <sub>J</sub> = 125°C	T <sub>J</sub> = 25°C	—	700	—	A
			T <sub>J</sub> = 125°C	—	760	—	
Q <sub>rr</sub>	Reverse recovery charge	L <sub>s</sub> = 150 nH Inductive load	T <sub>J</sub> = 25°C	—	660	—	μC
			T <sub>J</sub> = 125°C	—	1040	—	
E <sub>rec(10%)</sub>	Reverse recovery energy <sup>(Note 1)</sup>	L <sub>s</sub> = 150 nH Inductive load	T <sub>J</sub> = 25°C	—	0.96	—	J
			T <sub>J</sub> = 125°C	—	1.50	—	
E <sub>rec</sub>	Reverse recovery energy	L <sub>s</sub> = 150 nH Inductive load	T <sub>J</sub> = 25°C	—	1.10	—	J
			T <sub>J</sub> = 125°C	—	1.70	—	

**THERMAL CHARACTERISTICS**

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$R_{th(j-c)}$	Thermal resistance	Junction to Case (per 1/2 module)	—	—	30.0	K/kW
$R_{th(c-s)}$	Contact thermal resistance	Case to heat sink, $\lambda_{grease} = 1$ W/m $\cdot$ k $D_{(c-s)} = 100$ $\mu\text{m}$ (per 1/2 module)	—	24.0	—	K/kW

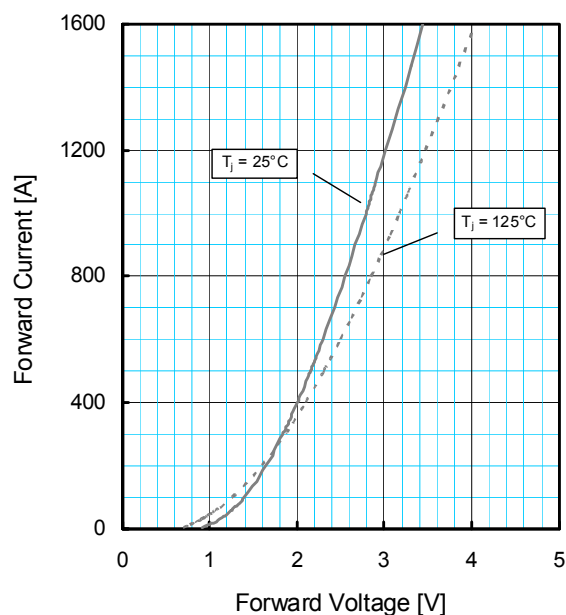
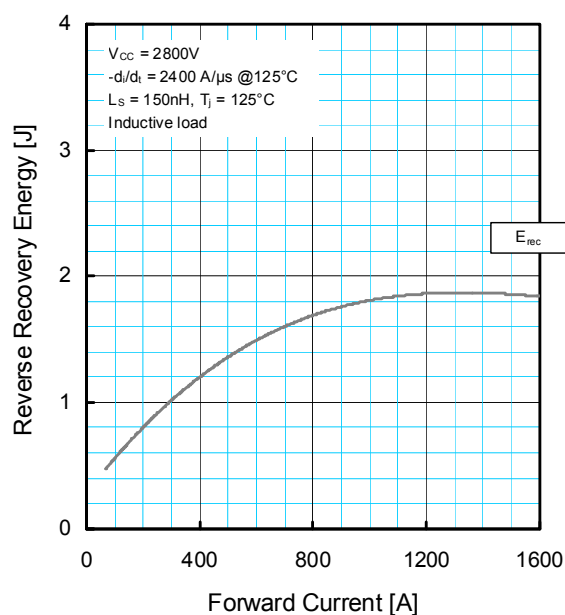
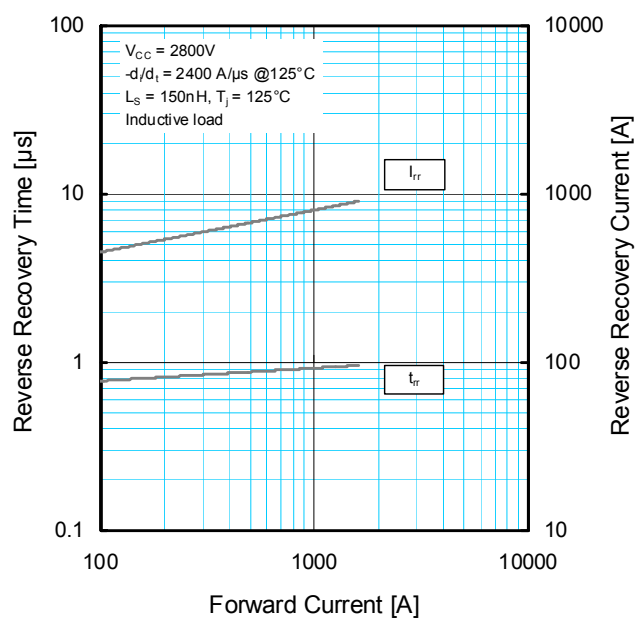
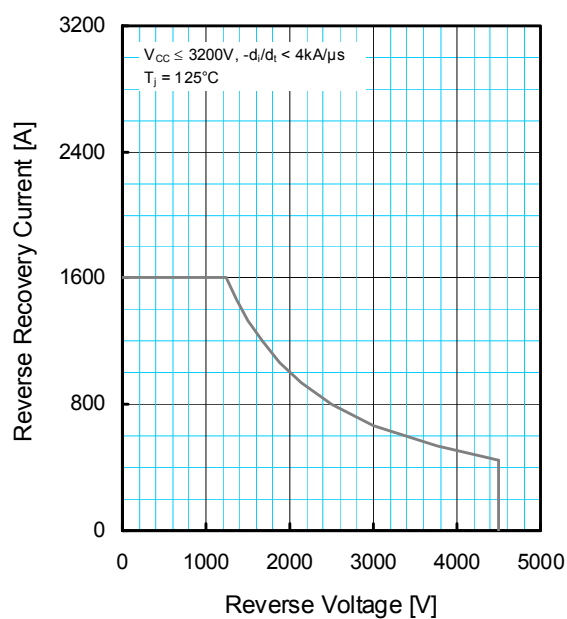
**MECHANICAL CHARACTERISTICS**

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$M_t$	Mounting torque	M8 : Main terminals screw	7.0	—	22.0	N $\cdot$ m
$M_s$		M6 : Mounting screw	3.0	—	6.0	N $\cdot$ m
$m$	Mass		—	1.0	—	kg
CTI	Comparative tracking index		600	—	—	—
$d_a$	Clearance		26.0	—	—	mm
$d_s$	Creepage distance		56.0	—	—	mm
$L_{PAK}$	Parasitic stray inductance		—	22.0	—	nH
$R_{AA+KK'}$	Internal lead resistance	$T_c = 25^\circ\text{C}$	—	0.14	—	m $\Omega$

Note 1.  $E_{rec(10\%)}$  are the integral of  $0.1V_R \times 0.1I_F \times dt$ .

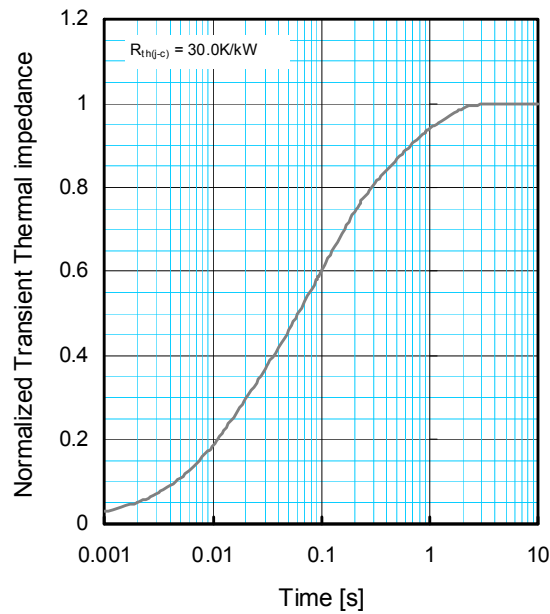
Note 2. Definition of all items is according to IEC 60747, unless otherwise specified.

## PERFORMANCE CURVES

**FORWARD CHARACTERISTICS (TYPICAL)****REVERSE RECOVERY ENERGY CHARACTERISTICS (TYPICAL)****REVERSE RECOVERY CHARACTERISTICS (TYPICAL)****REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)**

PERFORMANCE CURVES

TRANSIENT THERMAL IMPEDANCE  
CHARACTERISTICS



$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i \left\{ 1 - \exp\left(-\frac{t}{\tau_i}\right) \right\}$$

	1	2	3	4
$R_i$ [K/kW]	0.0055	0.2360	0.4680	0.2905
$\tau_i$ [sec]	0.0001	0.0131	0.0878	0.6247

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